## 502804515 05/12/2014

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2851111

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY AGREEMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
EASTMAN KODAK COMPANY	05/05/2014
FAR EAST DEVELOPMENT LTD	05/05/2014
FPC INC.	05/05/2014
KODAK (NEAR EAST), INC.	05/05/2014
KODAK AMERICAS, LTD.	05/05/2014
KODAK IMAGING NETWORK, INC.	05/05/2014
KODAK PORTUGUESA LIMITED	05/05/2014
KODAK REALTY, INC.	05/05/2014
LASER-PACIFIC MEDIA CORPORATION	05/05/2014
QUALEX INC.	05/05/2014
KODAK PHILIPPINES, LTD.	05/05/2014
NPEC INC.	05/05/2014
KODAK AVIATION LEASING LLC	05/05/2014

#### **RECEIVING PARTY DATA**

Name:	JPMORGAN CHASE BANK, N.A. AS ADMINISTRATIVE AGENT
Street Address:	500 STANTON CHRISTIANA ROAD, OPS 2, FLOOR 03
City:	NEWARK
State/Country:	DELAWARE
Postal Code:	19713-2107

## **PROPERTY NUMBERS Total: 31**

Property Type	Number
Application Number:	14217539
Application Number:	14217544
Application Number:	14217546
Application Number:	14222699
Application Number:	14226053
Application Number:	14225476
Application Number:	14228794
Application Number:	14230107
Application Number:	14230021
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**PATENT** 

502804515 REEL: 032869 FRAME: 0181

Property Type	Number
Application Number:	14230024
Application Number:	14230114
Application Number:	14230127
Application Number:	14230140
Application Number:	14230153
Application Number:	14243153
Application Number:	14244941
Application Number:	14246202
Application Number:	14246227
Application Number:	14350462
Application Number:	14248374
Application Number:	14248378
Application Number:	14249390
Application Number:	14253929
Application Number:	14253905
Application Number:	14253939
Application Number:	14253910
Application Number:	14261465
Application Number:	14261490
Application Number:	14264499
Application Number:	14264545
Application Number:	14265418

#### **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

US IVIAII.

Email: us-patent@kodak.com

Correspondent Name: EASTMAN KODAK COMPANY

Address Line 1: 343 STATE STREET

Address Line 4: ROCHESTER, NEW YORK 14650-2201

ATTORNEY DOCKET NUMBER:	SEC/JPMORGAN
NAME OF SUBMITTER:	KAREN M. PISA
SIGNATURE:	/Karen M. Pisa/
DATE SIGNED:	05/12/2014

#### **Total Attachments: 7**

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#### INTELLECTUAL PROPERTY SECURITY AGREEMENT

This INTELLECTUAL PROPERTY SECURITY AGREEMENT (as amended, amended and restated, supplemented or otherwise modified from time to time, the "IP Security Agreement") dated May 5, 2014, is made by the Persons listed on the signature pages hereof (collectively, the "Grantors") in favor of JPMorgan Chase Bank, N.A., as Administrative Agent (the "Administrative Agent") for the Secured Parties (as defined in the Credit Agreement referred to below).

WHEREAS, Eastman Kodak Company, a New Jersey corporation, has entered into a Senior Secured First Lien Term Credit Agreement dated as of September 3, 2013 (as amended, amended and restated, supplemented or otherwise modified from time to time, the "Credit Agreement"), with JPMorgan Chase Bank, N.A., as Administrative Agent, and the Lenders party thereto. Terms defined in the Credit Agreement and not otherwise defined herein are used herein as defined in the Credit Agreement.

WHEREAS, as a condition precedent to the obligation of the Lenders to make their respective extensions of credit to the Borrower under the Credit Agreement, each Grantor has executed and delivered that certain Guarantee and Collateral Agreement dated September 3, 2013, made by the Grantors to the Administrative Agent (as amended, amended and restated, supplemented or otherwise modified from time to time, the "Security Agreement").

WHEREAS, under the terms of the Security Agreement, the Grantors have granted to the Administrative Agent, for the ratable benefit of the Secured Parties, a security interest in, among other property, certain intellectual property of the Grantors, and have agreed as a condition thereof to execute this IP Security Agreement for recording with the United States Copyright Office, the United States Patent and Trademark Office and other governmental authorities.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each Grantor agrees as follows:

- SECTION 1. <u>Grant of Security</u>. Each Grantor hereby grants to the Administrative Agent for the ratable benefit of the Secured Parties a security interest in all of such Grantor's right, title and interest in and to the following (the "*Collateral*"):
- (i) the patents and patent applications and all exclusive patent licenses set forth in Schedule A hereto (the "*Patents*");
- (ii) the trademark and service mark registrations and applications and all exclusive trademark licenses set forth in Schedule B hereto (provided that no security interest shall be granted in United States intent-to-use trademark applications to the extent that, and solely during the period in which, the grant of a security interest therein would impair the validity or enforceability of such intent-to-use trademark applications under applicable federal law), together with the goodwill symbolized thereby (the "*Trademarks*");
  - (iii) all copyrights, whether registered or unregistered, now owned or hereafter

acquired by such Grantor, including the copyright registrations and applications and exclusive copyright licenses set forth in Schedule C hereto (the "Copyrights");

- (iv) all reissues, divisions, continuations, continuations-in-part, extensions, renewals and reexaminations of any of the foregoing, all rights in the foregoing provided by international treaties or conventions, all rights corresponding thereto throughout the world and all other rights of any kind whatsoever of such Grantor accruing thereunder or pertaining thereto;
- (v) any and all claims for damages and injunctive relief for past, present and future infringement, dilution, misappropriation, violation, misuse or breach with respect to any of the foregoing, with the right, but not the obligation, to sue for and collect, or otherwise recover, such damages; and
- (vi) any and all proceeds of, collateral for, income, royalties and other payments now or hereafter due and payable with respect to, and supporting obligations relating to, any and all of the Collateral of or arising from any of the foregoing.
- SECTION 2. Security for Obligations. The grant of a security interest in, the Collateral by each Grantor under this IP Security Agreement secures the payment of all obligations of such Grantor now or hereafter existing under or in respect of the Loan Documents, whether direct or indirect, absolute or contingent, and whether for principal, reimbursement obligations, interest, premiums, penalties, fees, indemnifications, contract causes of action, costs, expenses or otherwise. Without limiting the generality of the foregoing, this IP Security Agreement secures, as to each Grantor, the payment of all amounts that constitute part of the Obligations and that would be owed by such Grantor to any Secured Party under the Loan Documents but for the fact that such Obligations are unenforceable or not allowable due to the existence of a bankruptcy, reorganization or similar proceeding involving a Loan Party.
- SECTION 3. <u>Recordation</u>. Each Grantor authorizes and requests that the Register of Copyrights, and the Commissioner for Patents or Trademarks record this IP Security Agreement.
- SECTION 4. <u>Execution in Counterparts</u>. This IP Security Agreement may be executed in any number of counterparts, each of which when so executed shall be deemed to be an original and all of which taken together shall constitute one and the same agreement.
- SECTION 5. Grants, Rights and Remedies. This IP Security Agreement has been entered into in conjunction with the provisions of the Security Agreement. Each Grantor does hereby acknowledge and confirm that the grant of the security interest hereunder to, and the rights and remedies of, the Administrative Agent with respect to the Collateral are more fully set forth in the Security Agreement, the terms and provisions of which are incorporated herein by reference as if fully set forth herein.
- SECTION 6. <u>Governing Law</u>. This IP Security Agreement shall be governed by, and construed in accordance with, the laws of the State of New York.

[Signature Page Follows]

IN WITNESS WHEREOF, each Grantor has caused this IP Security Agreement to be duly executed and delivered by its officer thereunto duly authorized as of the date first above written.

#### EASTMAN KODAK COMPANY

Name: William G. Love

Title: Treasurer

Address for Notices: Eastman Kodak Company 343 State Street Rochester, NY 14650

FAR EAST DEVELOPMENT LTD.
FPC INC.
KODAK (NEAR EAST), INC.
KODAK AMERICAS, LTD.
KODAK IMAGING NETWORK, INC.
KODAK PORTUGUESA LIMITED
KODAK REALTY, INC.
LASER-PACIFIC MEDIA CORPORATION
QUALEX INC.

Name: William G. Love

Title: Treasurer

Address for Notices: c/o Eastman Kodak Cor

c/o Eastman Kodak Company

343 State Street Rochester, NY 14650

[Signature Page to May 5, 2014 Intellectual Property Security Agreement]

# KODAK PHILIPPINES, LTD. NPEC INC.

By William M Jave

Name: William G. Love Title: Assistant Treasurer

Address for Notices: c/o Eastman Kodak Company 343 State Street Rochester, NY 14650

### KODAK AVIATION LEASING LLC

Name: William G. Love

Title: Manager

Address for Notices: c/o Eastman Kodak Company

343 State Street Rochester, NY 14650

# EXECUTION VERSION

## Schedule A

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4/16/2014	4/16/2014	4/16/2014	4/11/2014	4/10/2014	4/9/2014	4/9/2014	4/8/2014	4/8/2014	<i>47/2</i> 014	47/2014	4/4/2014	4/2/2014	4/1/2014	3/31/2014	3/31/2014	3/31/2014	3/31/2014	3/31/2014	3/31/2014	3/31/2014	3/31/2014	3/28/2014	3/26/2014	3/26/2014	3/24/2014	3/21/2014	3/18/2014	3/18/2014	3/18/2014	3/18/2014	Appin Date Patent Number
																															Grant Date
Eastman Kodak Company FORMING AN IMAGE ON A MEDIA	Eastman Kodak Company WRAP-AROUND MICRO-WIRE CIRCUIT STRUCTURE	Eastman Kodak Company DIGITAL EMBOSSING AND CREASING	Eastman Kodak Company ON-PRESS DEVEL	Eastman Kodak Company FORMING CONDUC	Eastman Kodak Company LOGIC GATE ARRAY	Eastman Kodak Company PRINTING ELECTRONIC CIRCUITRY LOGIC	Eastman Kodak Company MASK FORMING IMAGEABLE MATERIAL AND USE	Eastman Kodak Company A LITHOGRAPHIC s	Eastman Kodak Company METHOD FOR PREVENTING FLUTES ON A NON-PRINT SIDE	Eastman Kodak Company METHOD FOR PREVENTING FLUTES ON A PRINT SIDE	Eastman Kodak Company METHOD OF FLEX	Eastman Kodak Company DRIVE ROLLER CC	Eastman Kodak Company SILICON SUBSTRATE MEMS DEVICE	Eastman Kodak Company ALIGNMENT STRU	Eastman Kodak Company SYSTEM FOR FOR	Eastman Kodak Company METHOD FOR FOR	Easiman Kodak Company SYSTEM FOR ALIGNING PATTERNS ON A SUBSTRATE	Eastman Kodak Company HIGH-ASPECT-RATIO IMPRINTED STRUCTURE METHOD	Eastman Kodak Company HIGH-ASPECT-RATIO IMPRINTED STRUCTURE	Eastman Kodak Company METHOD FOR ALIGNING PATTERNS ON A SUBSTRATE	Eastman Kodak Company PRINTHEAD INCLU	Eastman Kodak Company ENHANCED COLO	Eastman Kodak Company REDUCING HALO ARTIFACTS IN	Eastman Kodak Company METHOD FOR DET	Eastman Kodak Company WEB GUIDING STF	Easiman Kodak Company INKJET RECEIVER PRECOATS INCORPORATING SILICA	Eastman Kodak Company MULTHAREA MICRO-WIRE STRUCTURE	Eastman Kodak Company MULTHLAYER MICRO-WIRE STRUCTURE	Eastman Kodak Company MAKING MULTI-LAYER MICRO-WIRE STRUCTURE	Eastman Kodak Company THIOSULFATE POLYMERS	Current Owner Title
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**RECORDED: 05/12/2014** 

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